



## Product Change Notification / LIAL-02EMAI368

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### Date:

16-Nov-2020

### Product Category:

Access Networks, Broadband Gateway, Line Drivers

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 3886.005, and 3886.006 Final Notice: Qualification of MMT as an additional assembly site for selected Microsemi products available in 28L VQFN (4x5x1mm) and 16L VQFN (4x4x1mm) packages

### Affected CPNs:

[LIAL-02EMAI368\\_Affected\\_CPN\\_11162020.pdf](#)  
[LIAL-02EMAI368\\_Affected\\_CPN\\_11162020.csv](#)

### Notification Text:

**PCN Status:** Final notification.

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of MMT as an additional assembly site for selected Microsemi products available in 28L VQFN (4x5x1mm) and 16L VQFN (4x4x1mm) packages.

#### Pre Change:

Assembled at ASEM using palladium coated copper wire (PdCu) bond wire or palladium coated copper wire with gold flash (CuPdAu) bond wire, CRM1076DS die attach, and CEL-9240HF10AK-G1 mold compound material or assembled at UNIC using palladium coated copper wire (PdCu) bond wire, 8290 die attach, and G770HP mold compound material.

#### Post Change:

Assembled at ASEM using palladium coated copper wire (PdCu) bond wire or palladium coated copper wire with gold flash

(CuPdAu) bond wire, CRM1076DS die attach, and CEL-9240HF10AK-G1 mold compound material or assembled at UNIC using palladium coated copper wire (PdCu) bond wire, 8290 die attach, and G770HP mold compound material or assembled at MMT using or palladium coated copper wire with gold flash (CuPdAu) bond wire wire material, 3280 die attach, and G700LTD mold compound material.

**Pre and Post Change Summary:**

	Pre Change			Post Change			
<b>Assembly Site</b>	ASE Group -Malaysia (ASEM)		Unisem Chengdu Co.,Ltd. (UNIC)	ASE Group -Malaysia (ASEM)		Unisem Chengdu Co.,Ltd. (UNIC)	Microchip Technology Thailand (Branch) (MMT)
<b>Wire material</b>	PdCu	CuPdAu	PdCu	PdCu	CuPdAu	PdCu	CuPdAu
<b>Die attach material</b>	CRM1076DS		8290	CRM1076DS		8290	3280
<b>Molding compound material</b>	CEL-9240HF10AK-G1		G770HP	CEL-9240HF10AK-G1		G770HP	G700LTD
<b>Lead frame material</b>	A194		A194	A194		A194	A194
<b>LF drawing comparison</b>	See Pre and Post Change attachment.						

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve productivity and on-time delivery by qualifying MMT as an additional assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**December 7, 2020 (date code: 2050)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	November 2020				December 2020				
Workweek	45	46	47	48	49	50	51	52	53
Final PCN Issue Date			X						
Qual Report Availability			X						
Estimated						X			

Implementation Date									
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**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:November 16, 2020:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on December 7, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[PCN\\_LIAL-02EMAI368 Qual Report.pdf](#)  
[PCN\\_LIAL-02EMAI368 \\_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

LE87402MQC  
LE87402MQCT  
LE87270NQC  
LE87270NQCT  
LE87285NQC  
LE87285NQCT  
LE87557NQC  
LE87557NQCT  
LE87100NQC  
LE87100NQCT  
LE87502MQC  
LE87502MQCT  
LE87282MQC  
LE87282MQCT  
LE87612MQC  
LE87612MQCT  
LE79271AMQC  
LE79271MQC  
LE79271AMQCT  
LE79271MQCT  
LE9551CMQC  
LE9551DMQC  
LE9551CMQCT  
LE9551DMQCT  
LE87511NQC  
LE87511NQCT  
LE87286NQC  
LE87286NQCT